



1. Electrode Exposure



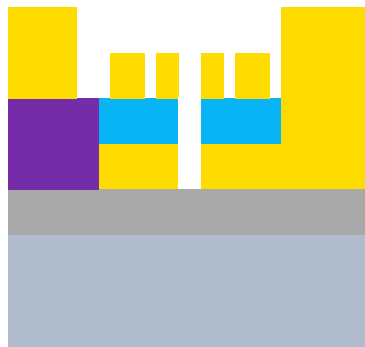
2. Active Area Etch



3. SiO<sub>2</sub> Backfill



4. 3x Metal Deposition



5. Release Window Etch



6. XeF<sub>2</sub> Release